Qualification Results Summary for LFCSP Package with Non-conductive Die Attach Epoxy at STATS ChipPAC China (SCC)

QUALIFICATION RESULTS			
Test	Conditions	Sample Size	Result
Highly Accelerated Stress Test (HAST)*	JEDEC *JESD22-A110*	3 x 77	**PASS**
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	3 x 77	**PASS**
Autoclave (AC)*	JEDEC *JESD22-A102*	3 x 77	**PASS**
Solder Heat Resistance (SHR)*	JEDEC/IPC *J-STD-020*	3 x 11	**PASS**
High Temperature Storage Life (HTSL)	JEDEC *JESD22-A103*	1 x 77	**PASS**
Field Induced Charged Device Model (FICDM)	JEDEC *JESD22-C101*	3/Voltage	**PASS ±1250V**

*Preconditioned per JEDEC/IPC J-STD-020